EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L2	441	(imperfect adj connection) or (discontinued adj areas)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L3	1	L1 and L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L4	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L5	11	takenaka-yuuichi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L6	6051819	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L7	598671	(insulat$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L8	280146	L7 and L6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L9	89	L8 and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L10	438531	resin and conduct$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L11	26	L9 and L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L12	194444	thermal near (expansion or expanding or expand)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L13	8	L12 and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L14	2	L11 and L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L15	1539	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L16	280	L15 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L17	1406	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L18	326	L17 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L19	7	L2 and "349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L20	54402	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L21	1	L1 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L22	6051819	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L23	598671	(insulat$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L24	280146	L22 and L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L25	6277529	gap or hole or (imperfect near connection) or space or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L26	283967	L25 and L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L27	1539	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L28	197	L26 and L27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L29	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L30	19937	L29 and L25 and L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L31	965	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L32	1	L30 and L31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L33	1406	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L34	12	L30 and L33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L35	965	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L36	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L37	1406	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L38	1539	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L39	1165	349/138.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L40	6051819	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L41	632	L39 and L40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L42	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L43	61416	L40 same L42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L44	10	L43 and L39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L45	378	349/142.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L46	354	349/150.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L47	2	L43 and L45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L48	57	L43 and L46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L49	295	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L50	164068	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L51	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L52	5394	L50 same L51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L53	39348	"349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L54	53	L52 and L53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L55	7049936	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L56	6060	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with L51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L57	1791	L55 same L56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L58	11	L53 and L57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L59	141279	L51 and L55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L60	1156	L59 and L53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L61	121	L60 and L50	USPAT	OR	ON	2006/05/25 17:53
L62	379563	Sharp Kabushiki Kaisha.As.	USPAT	OR	ON	2006/05/25 17:53
L63	54533	L62 and slot	USPAT	OR	ON	2006/05/25 17:53
L64	82	L62 and L57	USPAT	OR	ON	2006/05/25 17:53
L65	2	L64 and "349".clas.	USPAT	OR	ON	2006/05/25 17:53
L66	82234	thermal adj expan$5	USPAT	OR	ON	2006/05/25 17:53
L67	15028	"349".clas.	USPAT	OR	ON	2006/05/25 17:53
L68	573	L66 and L67	USPAT	OR	ON	2006/05/25 17:53
L69	492	L68 and L55	USPAT	OR	ON	2006/05/25 17:53

L70	147	L66 and L50 and L56 and L55	USPAT	OR	ON	2006/05/25 17:53
L71	7	("4506004" | "4715117" | "4728568" | "5591353" | "6272745" | "6276055" | "6631838").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L72	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L73	164068	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L74	7049936	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L75	6060	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with L72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L76	82234	thermal adj expan$5	USPAT	OR	ON	2006/05/25 17:53
L77	147	L76 and L73 and L75 and L74	USPAT	OR	ON	2006/05/25 17:53
L78	24293	TCP or (tape adj carrier adj package) or T-C-P	USPAT	OR	ON	2006/05/25 17:53
L79	5	L73 and L75 and L74 and L76 and L78	USPAT	OR	ON	2006/05/25 17:53
L80	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L81	8	L80 and L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L82	9	L73 and L75 and L74 and L78	USPAT	OR	ON	2006/05/25 17:53
L83	295	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L84	449	349/152.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L85	5997723	hannstar display corp.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L86	24	L85 and L77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L87	1	09/204130.app.	USPAT	OR	ON	2006/05/25 17:53
L88	59	("3913219" | "3947956" | "4416914" | "4555745" | "4566186" | "4632845" | "4774634" | "4808434" | "4870746" | "5225969" | "5298687" | "5305523" | "5347258" | "5354599" | "5384434" | "5428190" | "5502889" | "5527998" | "5599595" | "5688584" | "5716663" | "5727310" | "5747222" | "5758575" | "5763058" | "5814366").PN. OR ("6021050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L89	3085	428/209.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L90	19	L89 and L77	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L91	1076	428/194.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L92	3875281	L74	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L93	513	L74 and L91	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L94	2	09/136201.app.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L95	4	L77 and "349".clas.	USPAT	OR	ON	2006/05/25 17:53
L96	70	L78 and (prevent$3 with L76)	USPAT	OR	ON	2006/05/25 17:53

EAST Search History

L97	3446	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L98	65	L97 and L75 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L99	86	multiplelayer or multiplelayering with L72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L100	48	L99 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L101	14483	prevent$3 same L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L102	11629	L101 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L103	74	L102 and L75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L104	11629	L101 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L105	4729785	(imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

L106	2781	L75 and L105	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L107	525	L106 and L73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L108	598671	(insulat$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L109	132	L108 and L78 and L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L110	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L111	1	"6738123".pn. and insulat$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L112	4	("6738123").URPN.	USPAT	OR	ON	2006/05/25 17:53
L113	6	("5745202" | "5969780" | "6198051" | "6198521" | "6369867" | "6573954").PN. OR ("6870589").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L114	54402	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L115	7	L114 and L78 and L75 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L116	19	("6121553").URPN.	USPAT	OR	ON	2006/05/25 17:53

L117	1	L115 and (semiconductor adj chip)	USPAT	OR	ON	2006/05/25 17:53
L118	0	10/624601.app.	USPAT	OR	ON	2006/05/25 17:53
L119	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L120	1	L119 and (semiconductor adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON ·	2006/05/25 17:53
L121	1	resin and 09/204130.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L122	28	((((imperfect or irregular) near part) or gap or hole or space) same (MLPCB or (Multi-layer$2 near PCB) or (multi$3 near layer$2 near printed near circuit near board)) same insulat$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:24
L123	0	L122 and 361/721.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:20
L124	0	((((imperfect or irregular) near part) or gap or hole or space) same (MLPCB or (Multi-layer$2 near PCB) or (multi$3 near layer$2 near printed near circuit near board))).clm. and 361/721.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:27
L125	56	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 361/721.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:27
L126	78	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 349/150.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:22
L127	44	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 345/206.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23

L128	76	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 349/151.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23
L129	547	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 428/209.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23
L130	92	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 428/194.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23
L131	79	((MLPCB or (Multi-layer$2 near PCB) or (multi$3 near layer$2 near printed near circuit near board)) same insulat$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:25
L132	445	((MLPCB or (Multi-layer$2 near PCB) or (multi$3 near layer$2 near printed near circuit near board))).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:25
L133	1	(L125 or L126 or L127 or L128 or L129 or L130) and L132	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:26
L134	5	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 361/78.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:27